ABSTRACT

The present invention provides a real-time automatic control method and system for silicon wafer production, a medium and a device. The solution includes: positioning a silicon rod through a robot to obtain a position of the silicon rod, setting a gluing speed target value to automatically glue and bond the silicon rod; automatically performing transportation and slicing through the robot; forming first target degummed silicon wafers through a degumming machine; arranging the first target degummed silicon wafers through a wafer arrangement machine, to form second target degummed silicon wafers; cleaning the second target degummed silicon wafers through a cleaning machine, to form cleaning-finished silicon wafers, and issuing a silicon wafer cleaning finished command; automatically completing classification and quality analysis of all silicon wafers through the robot after the robot fetches the silicon wafer cleaning finished command, and packaging and transporting them to a warehouse. Production efficiency and reliability of monocrystalline silicon wafers can be improved in the solution by means of online automatic control of a production process of the monocrystalline silicon wafers, in combination with automatic identification and judgment by the robot.

Fig. 1